Lattice Semiconductor Corporation - LFXP3C-4T100C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3000
Total RAM Bits	55296
Number of I/O	62
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp3c-4t100c

Slice

Each slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-3 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge/level clocks.

There are 14 input signals: 13 signals from routing and one from the carry-chain (from adjacent slice or PFU). There are 7 outputs: 6 to routing and one to carry-chain (to adjacent PFU). Table 2-1 lists the signals associated with each slice.

Figure 2-3. Slice Diagram

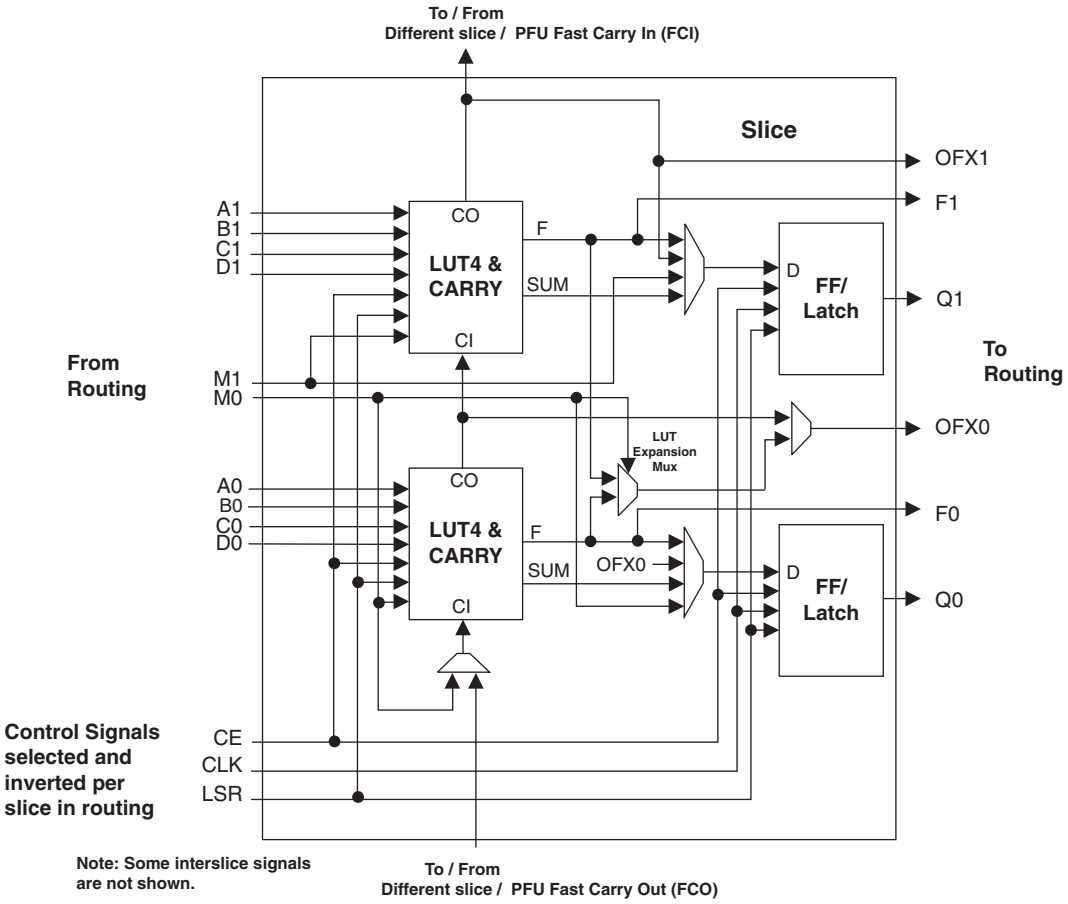

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM[1]	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

1. These modes are not available in PFF blocks

Routing

There are many resources provided in the LatticeXP devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. The x2 and x6 resources are buffered allowing both short and long connections routing between PFUs.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock Distribution Network

The clock inputs are selected from external I/O, the sysCLOCK™ PLLs or routing. These clock inputs are fed through the chip via a clock distribution system.

Primary Clock Sources

LatticeXP devices derive clocks from three primary sources: PLL outputs, dedicated clock inputs and routing. LatticeXP devices have two to four sysCLOCK PLLs, located on the left and right sides of the device. There are four dedicated clock inputs, one on each side of the device. Figure 2-5 shows the 20 primary clock sources.

Figure 2-10. PLL Diagram

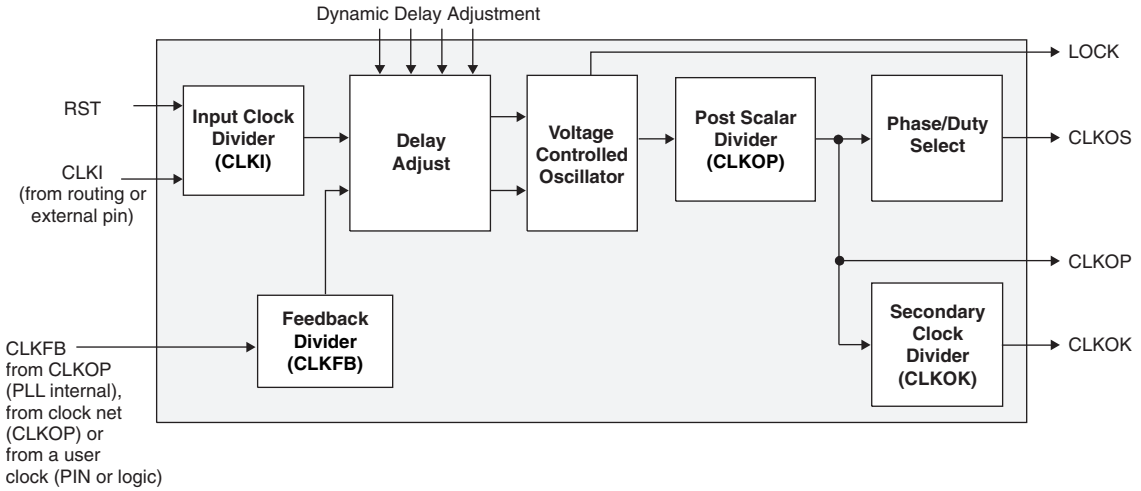

Figure 2-11 shows the available macros for the PLL. Table 2-11 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive

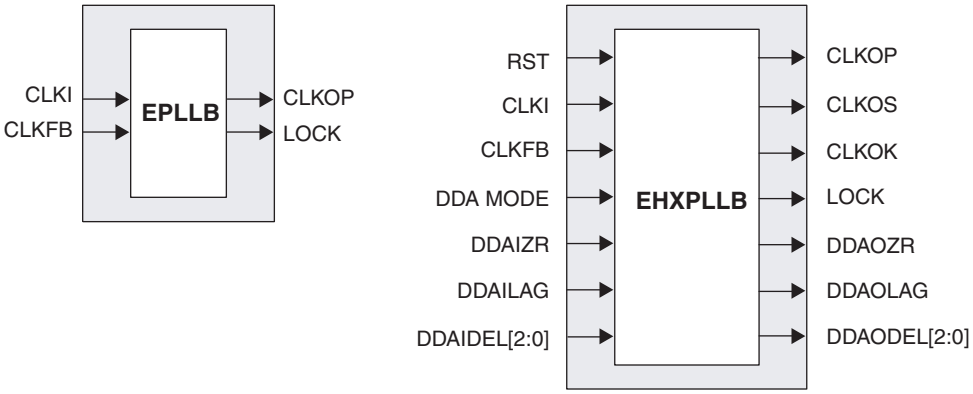

Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from CLKOP (PLL internal), from clock net (CLKOP) or from a user clock (PIN or logic)
RST	I	“1” to reset input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	“1” indicates PLL LOCK to CLKI
DDAMODE	I	Dynamic Delay Enable. “1” Pin control (dynamic), “0”: Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. “1”: delay = 0, “0”: delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. “1”: Lag, “0”: Lead
DDAIDEL[2:0]	I	Dynamic Delay Input
DDAOZR	O	Dynamic Delay Zero Output
DDAOLAG	O	Dynamic Delay Lag/Lead Output
DDAODEL[2:0]	O	Dynamic Delay Output

master serial clock is 2.5MHz. Table 2-10 lists all the available Master Serial Clock frequencies. When a different Master Serial Clock is selected during the design process, the following sequence takes place:

1. User selects a different Master Serial Clock frequency for configuration.
2. During configuration the device starts with the default (2.5MHz) Master Serial Clock frequency.
3. The clock configuration settings are contained in the early configuration bit stream.
4. The Master Serial Clock frequency changes to the selected frequency once the clock configuration bits are received.

For further information on the use of this oscillator for configuration, please see details of additional technical documentation at the end of this data sheet.

Table 2-10. Selectable Master Serial Clock (CCLK) Frequencies During Configuration

CCLK (MHz)	CCLK (MHz)	CCLK (MHz)
2.5[1]	13	45
4.3	15	51
5.4	20	55
6.9	26	60
8.1	30	130
9.2	34	—
10.0	41	—

1. Default

Density Shifting

The LatticeXP family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 2, 4]	Input or I/O Leakage	$0 \le V_{IN} \le (V_{CCIO} - 0.2V)$	—	—	10	µA
		$(V_{CCIO} - 0.2V) < V_{IN} \le 3.6V$	—	—	40	µA
I_{PU}	I/O Active Pull-up Current	$0 \le V_{IN} \le 0.7\ V_{CCIO}$	-30	—	-150	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\le V_{IN} \le V_{IH}$ (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low sustaining current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	-150	µA
V_{BHT}	Bus Hold trip Points	$0 \le V_{IN} \le V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C2	Dedicated Input Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. Not applicable to SLEEPN/TOE pin.
3. T_A 25°C, f = 1.0MHz
4. When V_{IH} is higher than V_{CCIO}, a transient current typically of 30ns in duration or less with a peak current of 6mA can be expected on the high-to-low transition.

Supply Current (Sleep Mode)[1, 2, 3]

Symbol	Parameter	Device	Typ.[4]	Max	Units
I_{CC}	Core Power Supply	LFXP3C	12	65	µA
		LFXP6C	14	75	µA
		LFXP10C	16	85	µA
		LFXP15C	18	95	µA
		LFXP20C	20	105	µA
I_{CCP}	PLL Power Supply (per PLL)	All LFXP 'C' Devices	1	5	µA
I_{CCAUX}	Auxiliary Power Supply	LFXP3C	2	90	µA
		LFXP6C	2	100	µA
		LFXP10C	2	110	µA
		LFXP15C	3	120	µA
		LFXP20C	4	130	µA
I_{CCIO}	Bank Power Supply[5]	LFXP3C	2	20	µA
		LFXP6C	2	22	µA
		LFXP10C	2	24	µA
		LFXP15C	3	27	µA
		LFXP20C	4	30	µA
I_{CCJ}	VCCJ Power Supply	All LFXP 'C' Devices	1	5	µA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.
2. Frequency 0MHz.
3. User pattern: blank.
4. T_A=25°C, power supplies at nominal voltage.
5. Per bank.

sysIO Recommended Operating Conditions

Standard	V_{CCIO}			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.135	3.3	3.465	—	—	—
LVCMOS 2.5	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.465	—	—	—
PCI33	3.135	3.3	3.465	—	—	—
SSTL18 Class I	1.71	1.8	1.89	0.833	0.9	0.969
SSTL2 Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15 Class III	1.425	1.5	1.575	—	0.9	—
HSTL 18 Class I, II	1.71	1.8	1.89	—	0.9	—
HSTL 18 Class III	1.71	1.8	1.89	—	1.08	—
LVDS	2.375	2.5	2.625	—	—	—
LVPECL[1]	3.135	3.3	3.465	—	—	—
BLVDS[1]	2.375	2.5	2.625	—	—	—

1. Inputs on chip. Outputs are implemented with the addition of external resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

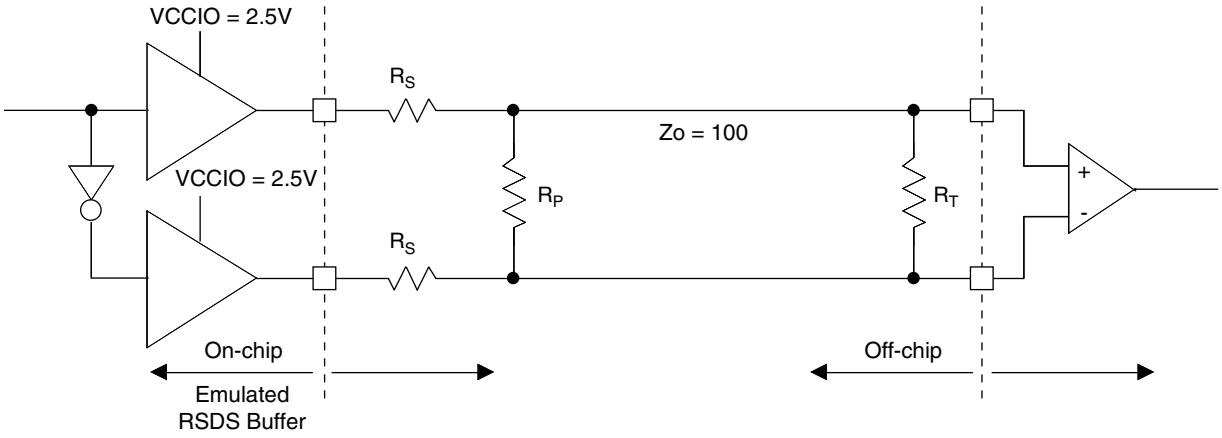

Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	ohms
R_S	Driver series resistor	300	ohms
R_P	Driver parallel resistor	121	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	ohms
I_{DC}	DC output current	3.66	mA

LatticeXP Internal Timing Parameters[1] (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.61	—	1.94	—	2.32	ns
PLL Parameters								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

Timing v.F0.11

LatticeXP Family Timing Adders[1]

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.5	0.5	0.5	ns
LVDS25	LVDS	0.4	0.4	0.4	ns
BLVDS25	BLVDS	0.5	0.5	0.5	ns
LVPECL33	LVPECL	0.6	0.6	0.6	ns
HSTL18_I	HSTL_18 class I	0.4	0.4	0.4	ns
HSTL18_II	HSTL_18 class II	0.4	0.4	0.4	ns
HSTL18_III	HSTL_18 class III	0.4	0.4	0.4	ns
HSTL18D_I	Differential HSTL 18 class I	0.4	0.4	0.4	ns
HSTL18D_II	Differential HSTL 18 class II	0.4	0.4	0.4	ns
HSTL18D_III	Differential HSTL 18 class III	0.4	0.4	0.4	ns
HSTL15_I	HSTL_15 class I	0.5	0.5	0.5	ns
HSTL15_III	HSTL_15 class III	0.5	0.5	0.5	ns
HSTL15D_I	Differential HSTL 15 class I	0.5	0.5	0.5	ns
HSTL15D_III	Differential HSTL 15 class III	0.5	0.5	0.5	ns
SSTL33_I	SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33_II	SSTL_3 class II	0.6	0.6	0.6	ns
SSTL33D_I	Differential SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33D_II	Differential SSTL_3 class II	0.6	0.6	0.6	ns
SSTL25_I	SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25_II	SSTL_2 class II	0.5	0.5	0.5	ns
SSTL25D_I	Differential SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25D_II	Differential SSTL_2 class II	0.5	0.5	0.5	ns
SSTL18_I	SSTL_18 class I	0.5	0.5	0.5	ns
SSTL18D_I	Differential SSTL_18 class I	0.5	0.5	0.5	ns
LVTTL33	LVTTL	0.2	0.2	0.2	ns
LVCMOS33	LVCMOS 3.3	0.2	0.2	0.2	ns
LVCMOS25	LVCMOS 2.5	0.0	0.0	0.0	ns
LVCMOS18	LVCMOS 1.8	0.1	0.1	0.1	ns
LVCMOS15	LVCMOS 1.5	0.1	0.1	0.1	ns
LVCMOS12	LVCMOS 1.2	0.1	0.1	0.1	ns
PCI33	PCI	0.2	0.2	0.2	ns
Output Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.3	0.3	0.3	ns
LVDS25	LVDS 2.5	0.3	0.3	0.3	ns
BLVDS25	BLVDS 2.5	0.3	0.3	0.3	ns
LVPECL33	LVPECL 3.3	0.1	0.1	0.1	ns
HSTL18_I	HSTL_18 class I	0.1	0.1	0.1	ns
HSTL18_II	HSTL_18 class II	0.1	0.1	0.1	ns
HSTL18_III	HSTL_18 class III	0.2	0.2	0.2	ns
HSTL18D_I	Differential HSTL 18 class I	0.1	0.1	0.1	ns
HSTL18D_II	Differential HSTL 18 class II	-0.1	-0.1	-0.1	ns
HSTL18D_III	Differential HSTL 18 class III	0.2	0.2	0.2	ns

LatticeXP Family Timing Adders[1] (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTL33_4mA	LVTTL 4mA drive	0.8	0.8	0.8	ns
LVTTL33_8mA	LVTTL 8mA drive	0.5	0.5	0.5	ns
LVTTL33_12mA	LVTTL 12mA drive	0.3	0.3	0.3	ns
LVTTL33_16mA	LVTTL 16mA drive	0.4	0.4	0.4	ns
LVTTL33_20mA	LVTTL 20mA drive	0.3	0.3	0.3	ns
LVCMOS33_2mA	LVCMOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVCMOS25_2mA	LVCMOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVCMOS18_2mA	LVCMOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVCMOS15_2mA	LVCMOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

1. General timing numbers based on LVCMOS 2.5, 12mA.

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LatticeXP sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Byte Data Flow				
t_{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7	—	ns
t_{HCBDI}	Byte D[0:7] Hold Time to CCLK	3	—	ns
t_{CODO}	Clock to Dout in Flowthrough Mode	—	12	ns
t_{SUCS}	CS[0:1] Setup Time to CCLK	7	—	ns
t_{HCS}	CS[0:1] Hold Time to CCLK	2	—	ns
t_{SUWD}	Write Signal Setup Time to CCLK	7	—	ns
t_{HWD}	Write Signal Hold Time to CCLK	2	—	ns
t_{DCB}	CCLK to BUSY Delay Time	—	12	ns
t_{CORD}	Clock to Out for Read Data	—	12	ns
sysCONFIG Byte Slave Clocking				
t_{BSCH}	Byte Slave Clock Minimum High Pulse	6	—	ns
t_{BSCL}	Byte Slave Clock Minimum Low Pulse	8	—	ns
t_{BSCYC}	Byte Slave Clock Cycle Time	15	—	ns
sysCONFIG Serial (Bit) Data Flow				
t_{SUSCDI}	DI (Data In) Setup Time to CCLK	7	—	ns
t_{HSCDI}	DI (Data In) Hold Time to CCLK	2	—	ns
t_{CODO}	Clock to Dout in Flowthrough Mode	—	12	ns
sysCONFIG Serial Slave Clocking				
t_{SSCH}	Serial Slave Clock Minimum High Pulse	6	—	ns
t_{SSCL}	Serial Slave Clock Minimum Low Pulse	6	—	ns
sysCONFIG POR, Initialization and Wake Up				
t_{ICFG}	Minimum Vcc to INIT High	—	50	ms
t_{VMC}	Time from t_{ICFG} to Valid Master Clock	—	2	us
t_{PRGMRJ}	Program Pin Pulse Rejection	—	7	ns
t_{PRGM}[2]	PROGRAMN Low Time to Start Configuration	25	—	ns
t_{DINIT}	INIT Low Time	—	1	ms
$t_{DPPINIT}$	Delay Time from PROGRAMN Low to INIT Low	—	37	ns
t_{DINITD}	Delay Time from PROGRAMN Low to DONE Low	—	37	ns
t_{IODISS}	User I/O Disable from PROGRAMN Low	—	25	ns
t_{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake-up Sequence	—	25	ns
t_{MWC}	Additional Wake Master Clock Signals after Done Pin High	120	—	cycles
Configuration Master Clock (CCLK)				
Frequency[1]		Selected Value - 30%	Selected Value + 30%	MHz
Duty Cycle		40	60	%

1. See Table 2-10 for available CCLK frequencies.
2. The threshold level for PROGRAMN, as well as for CFG[1] and CFG[0], is determined by V_{CC}, such that the threshold = $V_{CC}/2$.

Timing v.F0.11

Switching Test Conditions

Figure 3-13 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-13. Output Test Load, LVTTL and LVCMOS Standards

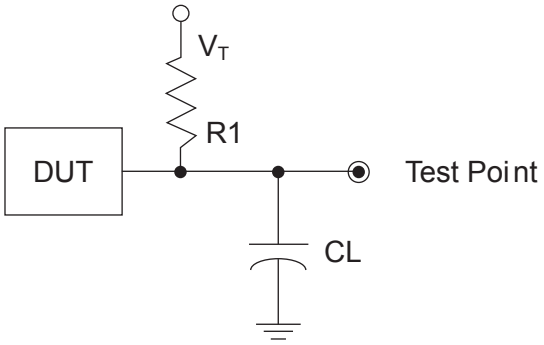

Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	∞	0pF	LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	188	0pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)			V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)			V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
93	PR9A	2	T	PCLKT2_0	PR12A	2	T	PCLKT2_0
94	PR8B	2	C	RUM0_PLLC_IN_A	PR8B	2	C	RUM0_PLLC_IN_A
95	PR8A	2	T	RUM0_PLLT_IN_A	PR8A	2	T	RUM0_PLLT_IN_A
96	PR7B	2	C[3]	-	PR7B	2	C[3]	-
97	PR7A	2	T[3]	DQS	PR7A	2	T[3]	DQS
98	VCCIO2	2	-	-	VCCIO2	2	-	-
99	PR6B	2	-	VREF1_2	PR6B	2	-	VREF1_2
100	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
101	GNDIO2	2	-	-	GNDIO2	2	-	-
102	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
103	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A
104	PR2B	2	C[3]	-	PR2B	2	C[3]	-
105	PR2A	2	T[3]	-	PR2A	2	T[3]	-
106	VCCAUX	-	-	-	VCCAUX	-	-	-
107	TDO	-	-	-	TDO	-	-	-
108	VCCJ	-	-	-	VCCJ	-	-	-
109	TDI	-	-	-	TDI	-	-	-
110	TMS	-	-	-	TMS	-	-	-
111	TCK	-	-	-	TCK	-	-	-
112	VCC	-	-	-	VCC	-	-	-
113	PT25A	1	-	VREF1_1	PT28A	1	-	VREF1_1
114	PT24A	1	-	-	PT27A	1	-	-
115	PT23A	1	-	D0	PT26A	1	-	D0
116	PT22B	1	C	D1	PT25B	1	C	D1
117	PT22A	1	T	VREF2_1	PT25A	1	T	VREF2_1
118	PT21A	1	-	D2	PT24A	1	-	D2
119	VCCIO1	1	-	-	VCCIO1	1	-	-
120	PT20B	1	-	D3	PT23B	1	-	D3
121	GNDIO1	1	-	-	GNDIO1	1	-	-
122	PT17A	1	-	D4	PT20A	1	-	D4
123	PT16A	1	-	D5	PT19A	1	-	D5
124	PT15B	1	C	D6	PT18B	1	C	D6
125	PT15A	1	T	-	PT18A	1	T	-
126	PT14B	1	-	D7	PT17B	1	-	D7
127	GND	-	-	-	GND	-	-	-
128	PT13B	0	C	BUSY	PT16B	0	C	BUSY
129	PT13A	0	T	CS1N	PT16A	0	T	CS1N
130	PT12B	0	C	PCLKC0_0	PT15B	0	C	PCLKC0_0
131	PT12A	0	T	PCLKT0_0	PT15A	0	T	PCLKT0_0
132	PT11B	0	C	-	PT14B	0	C	-
133	VCCIO0	0	-	-	VCCIO0	0	-	-
134	PT11A	0	T	DQS	PT14A	0	T	DQS
135	PT9A	0	-	DOUT	PT12A	0	-	DOUT
136	GNDIO0	0	-	-	GNDIO0	0	-	-
137	PT8A	0	-	WRITEN	PT11A	0	-	WRITEN
138	PT7A	0	-	VREF1_0	PT10A	0	-	VREF1_0

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
F5	PROGRAMN	7	-	-	PROGRAMN	7	-	-
E3	CCLK	7	-	-	CCLK	7	-	-
C1	PL2B	7	-	-	PL2B	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
G5	PL3A	7	T[3]	-	PL3A	7	T[3]	-
G6	PL3B	7	C[3]	-	PL3B	7	C[3]	-
F4	PL4A	7	T	-	PL4A	7	T	-
F3	PL4B	7	C	-	PL4B	7	C	-
G4	PL5A	7	T[3]	-	PL5A	7	T[3]	-
G3	PL5B	7	C[3]	-	PL5B	7	C[3]	-
D1	PL6A	7	T[3]	-	PL6A	7	T[3]	-
D2	PL6B	7	C[3]	-	PL6B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
E1	PL7A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A
E2	PL7B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A
H5	PL8A	7	T[3]	-	PL8A	7	T[3]	-
H6	PL8B	7	C[3]	-	PL8B	7	C[3]	-
H4	PL9A	7	-	-	PL9A	7	-	-
H3	PL10B	7	-	VREF1_7	PL10B	7	-	VREF1_7
F1	PL11A	7	T[3]	DQS	PL11A	7	T[3]	DQS
F2	PL11B	7	C[3]	-	PL11B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
J5	PL12A	7	T	-	PL12A	7	T	-
J6	PL12B	7	C	-	PL12B	7	C	-
G1	PL13A	7	T[3]	-	PL13A	7	T[3]	-
G2	PL13B	7	C[3]	-	PL13B	7	C[3]	-
J4	PL15A	7	T[3]	-	PL15A	7	T[3]	-
J3	PL15B	7	C[3]	-	PL15B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
H1	PL16A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A
H2	PL16B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A
J1	PL17A	7	T[3]	-	PL17A	7	T[3]	-
J2	PL17B	7	C[3]	-	PL17B	7	C[3]	-
K3	PL18A	7	-	VREF2_7	PL18A	7	-	VREF2_7
K2	PL19B	7	-	-	PL19B	7	-	-
K4	PL20A	7	T[3]	DQS	PL20A	7	T[3]	DQS
-	GNDIO7	7	-	-	GNDIO7	7	-	-
K5	PL20B	7	C[3]	-	PL20B	7	C[3]	-
K1	PL21A	7	T	-	PL21A	7	T	-
L2	PL21B	7	C	-	PL21B	7	C	-
L4	PL22A	7	T[3]	-	PL22A	7	T[3]	-
L3	PL22B	7	C[3]	-	PL22B	7	C[3]	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
T6	PL41A	6	T	-	PL45A	6	T	-
T5	PL41B	6	C	-	PL45B	6	C	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U3	PL42A	6	T[3]	-	PL46A	6	T[3]	-
U4	PL42B	6	C[3]	-	PL46B	6	C[3]	-
V4	PL43A	6	-	-	PL47A	6	-	-
W4	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-
W5	INITN	5	-	-	INITN	5	-	-
Y3	-	-	-	-	PB3B	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U5	-	-	-	-	PB4A	5	T	-
V5	-	-	-	-	PB4B	5	C	-
Y4	-	-	-	-	PB5A	5	T	-
Y5	-	-	-	-	PB5B	5	C	-
V6	-	-	-	-	PB6A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U6	-	-	-	-	PB6B	5	C	-
W6	PB3A	5	T	-	PB7A	5	T	-
Y6	PB3B	5	C	-	PB7B	5	C	-
AA2	PB4A	5	T	-	PB8A	5	T	-
AA3	PB4B	5	C	-	PB8B	5	C	-
V7	PB5A	5	-	-	PB9A	5	-	-
U7	PB6B	5	-	-	PB10B	5	-	-
Y7	PB7A	5	T	DQS	PB11A	5	T	DQS
W7	PB7B	5	C	-	PB11B	5	C	-
AA4	PB8A	5	T	-	PB12A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA5	PB8B	5	C	-	PB12B	5	C	-
AB3	PB9A	5	T	-	PB13A	5	T	-
AB4	PB9B	5	C	-	PB13B	5	C	-
AA6	PB10A	5	T	-	PB14A	5	T	-
AA7	PB10B	5	C	-	PB14B	5	C	-
U8	PB11A	5	T	-	PB15A	5	T	-
V8	PB11B	5	C	-	PB15B	5	C	-
Y8	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
W8	PB12B	5	C	-	PB16B	5	C	-
V9	PB13A	5	-	-	PB17A	5	-	-
U9	PB14B	5	-	-	PB18B	5	-	-
Y9	PB15A	5	T	DQS	PB19A	5	T	DQS
W9	PB15B	5	C	-	PB19B	5	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB19	PB37A	4	-	-	PB41A	4	-	-
AB20	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
V15	PB39A	4	T	DQS	PB43A	4	T	DQS
U15	PB39B	4	C	-	PB43B	4	C	-
Y15	PB40A	4	T	-	PB44A	4	T	-
W15	PB40B	4	C	-	PB44B	4	C	-
AA16	PB41A	4	T	-	PB45A	4	T	-
AA17	PB41B	4	C	-	PB45B	4	C	-
AA18	PB42A	4	T	-	PB46A	4	T	-
AA19	PB42B	4	C	-	PB46B	4	C	-
Y16	PB43A	4	T	-	PB47A	4	T	-
W16	PB43B	4	C	-	PB47B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA20	PB44A	4	T	-	PB48A	4	T	-
AA21	PB44B	4	C	-	PB48B	4	C	-
Y17	PB45A	4	-	-	PB49A	4	-	-
Y18	PB46B	4	-	-	PB50B	4	-	-
Y19	PB47A	4	T	DQS	PB51A	4	T	DQS
Y20	PB47B	4	C	-	PB51B	4	C	-
V16	PB48A	4	T	-	PB52A	4	T	-
U16	PB48B	4	C	-	PB52B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
U18	-	-	-	-	PB53A	4	T	-
V18	-	-	-	-	PB53B	4	C	-
W19	-	-	-	-	PB54A	4	T	-
W18	-	-	-	-	PB54B	4	C	-
U17	-	-	-	-	PB55A	4	T	-
V17	-	-	-	-	PB55B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
W17	-	-	-	-	PB56A	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
V19	PR43A	3	-	-	PR47A	3	-	-
U20	PR42B	3	C[3]	-	PR46B	3	C[3]	-
U19	PR42A	3	T[3]	-	PR46A	3	T[3]	-
V20	PR41B	3	C	-	PR45B	3	C	-
W20	PR41A	3	T	-	PR45A	3	T	-
T17	PR40B	3	C[3]	-	PR44B	3	C[3]	-
T18	PR40A	3	T[3]	-	PR44A	3	T[3]	-
T19	PR39B	3	C[3]	-	PR43B	3	C[3]	-
T20	PR39A	3	T[3]	-	PR43A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
R18	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
R17	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A
Y22	PR37B	3	C[3]	-	PR41B	3	C[3]	-
Y21	PR37A	3	T[3]	DQS	PR41A	3	T[3]	DQS
W22	PR36B	3	-	-	PR40B	3	-	-
W21	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
P17	PR34B	3	C[3]	-	PR38B	3	C[3]	-
P18	PR34A	3	T[3]	-	PR38A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
R19	PR33B	3	C	-	PR37B	3	C	-
R20	PR33A	3	T	-	PR37A	3	T	-
V22	PR32B	3	C[3]	-	PR36B	3	C[3]	-
V21	PR32A	3	T[3]	-	PR36A	3	T[3]	-
U22	PR30B	3	C[3]	-	PR34B	3	C[3]	-
U21	PR30A	3	T[3]	-	PR34A	3	T[3]	-
P19	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
P20	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
T22	PR28B	3	C[3]	-	PR32B	3	C[3]	-
T21	PR28A	3	T[3]	DQS	PR32A	3	T[3]	DQS
R22	PR27B	3	-	-	PR31B	3	-	-
R21	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
N19	PR25B	3	C[3]	-	PR29B	3	C[3]	-
N20	PR25A	3	T[3]	-	PR29A	3	T[3]	-
N18	PR24B	3	C	-	PR28B	3	C	-
M18	PR24A	3	T	-	PR28A	3	T	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P22	PR23B	3	C[3]	-	PR27B	3	C[3]	-
P21	PR23A	3	T[3]	-	PR27A	3	T[3]	-
N22	-	-	-	-	PR26B	3	C[3]	-
N21	-	-	-	-	PR26A	3	T[3]	-
M19	-	-	-	-	PR25B	3	-	-
M20	GNDP1	-	-	-	GNDP1	-	-	-
L18	VCCP1	-	-	-	VCCP1	-	-	-
M21	-	-	-	-	PR24A	2	-	-
M22	PR22B	2	C[3]	-	PR23B	2	C[3]	-
L22	PR22A	2	T[3]	-	PR23A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
L19	-	-	-	-	PR22B	2	C[3]	-
L20	-	-	-	-	PR22A	2	T[3]	-
L21	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
K22	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0

LatticeXP Family Data Sheet Ordering Information

December 2005 Data Sheet DS1001

Part Number Description

LFXP XX X – X XXXXXX X

Device Family
LatticeXP FPGA

Logic Capacity
3K LUTs = 3
6K LUTs = 6
10K LUTs = 10
15K LUTs = 15
20K LUTs = 20

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked per table below.

Grade
C = Commercial
I = Industrial

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F388 = 388-ball fpBGA
F484 = 484-ball fpBGA

TN100 = 100-pin Lead-free TQFP
TN144 = 144-pin Lead-free TQFP
QN208 = 208-pin Lead-free PQFP
FN256 = 256-ball Lead-free fpBGA
FN388 = 388-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA

Speed
3 = Slowest
4
5 = Fastest

Ordering Information (Contact Factory for Specific Device Availability)

Note:þLatticeXP devices are dual marked. For example, the commercial speed grade LFXP10E-4F256C is also marked with industrial grade -3I (LFXP10E-3F256I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3F484I	300	1.2V	-3	fpBGA	484	IND	15.5K
LFXP15E-4F484I	300	1.2V	-4	fpBGA	484	IND	15.5K
LFXP15E-3F388I	268	1.2V	-3	fpBGA	388	IND	15.5K
LFXP15E-4F388I	268	1.2V	-4	fpBGA	388	IND	15.5K
LFXP15E-3F256I	188	1.2V	-3	fpBGA	256	IND	15.5K
LFXP15E-4F256I	188	1.2V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3F484I	340	1.2V	-3	fpBGA	484	IND	19.7K
LFXP20E-4F484I	340	1.2V	-4	fpBGA	484	IND	19.7K
LFXP20E-3F388I	268	1.2V	-3	fpBGA	388	IND	19.7K
LFXP20E-4F388I	268	1.2V	-4	fpBGA	388	IND	19.7K
LFXP20E-3F256I	188	1.2V	-3	fpBGA	256	IND	19.7K
LFXP20E-4F256I	188	1.2V	-4	fpBGA	256	IND	19.7K